Preferred Device

Power MOSFET 2.0 Amps, 60 Volts

N-Channel SOT-223

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

Applications

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	60	Vdc
Drain-to-Gate Voltage (RGS = 1.0 M Ω)	V _{DGR}	60	Vdc
Gate–to–Source Voltage – Continuous – Non–repetitive (t _p ≤ 10 ms)	V _{GS}	± 20 ± 30	Vdc Vpk
Drain Current - Continuous @ $T_A = 25^{\circ}C$ - Continuous @ $T_A = 100^{\circ}C$ - Single Pulse ($t_p \le 10 \ \mu s$)	I _D	2.0 1.2 6.0	Adc Apk
Total Power Dissipation @ T _A = 25°C (Note 1.) Total Power Dissipation @ T _A = 25°C (Note 2.) Derate above 25°C	PD	2.1 1.3 0.014	W W W/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to 175	°C
Single Pulse Drain-to-Source Avalanche Energy - Starting T _J = 25°C (V _{DD} = 25 Vdc, V _{GS} = 10 Vdc, I _L (pk) = 6.0 Apk, L = 10 mH, V _{DS} = 60 Vdc)	E _{AS}	65	mJ
Thermal Resistance – Junction to Ambient (Note 1.) – Junction to Ambient (Note 2.)	R _θ JA R _θ JA	72.3 114	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	TL	260	°C

- When surface mounted to an FR4 board using 1" pad size, (Cu. Area 1.127 in²).
- When surface mounted to an FR4 board using minimum recommended pad size, 2–2.4 oz. (Cu. Area 0.272 in²).

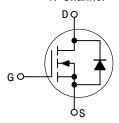


ON Semiconductor™

http://onsemi.com

2.0 AMPERES 60 VOLTS RDS(on) = 160 m Ω

N-Channel



MARKING DIAGRAM

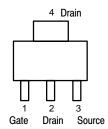


SOT-223 CASE 318E STYLE 3



5160 = Device Code L = Location Code WW = Work Week

PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping	
NTF3055-160T1	SOT-223	1000 Tape & Reel	
NTF3055-160T3	SOT-223	4000 Tape & Reel	
NTF3055-160T3LF	SOT-223	4000 Tape & Reel	

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

Charac	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = 250 μAdc) Temperature Coefficient (Positive)	V(BR)DSS	60 -	72 72	_ _	Vdc mV/°C	
Zero Gate Voltage Drain Current (VDS = 60 Vdc, VGS = 0 Vdc) (VDS = 60 Vdc, VGS = 0 Vdc, TJ =	IDSS	- -	- -	1.0 10	μAdc	
Gate-Body Leakage Current (VG	S = ± 20 Vdc, V _{DS} = 0 Vdc)	IGSS	-	-	± 100	nAdc
ON CHARACTERISTICS (Note 3.)						
Gate Threshold Voltage (Note 3.) (V _{DS} = V _{GS} , I _D = 250 μAdc) Threshold Temperature Coefficient (N	VGS(th)	2.0 -	3.1 6.6	4.0 -	Vdc mV/°C	
Static Drain-to-Source On-Resistan (VGS = 10 Vdc, I _D = 1.0 Adc)	R _{DS(on)}	-	142	160	mΩ	
Static Drain-to-Source On-Resistance (Note 3.) (VGS = 10 Vdc, ID = 2.0 Adc) (VGS = 10 Vdc, ID = 1.0 Adc, TJ = 150°C)		V _{DS(on)}	-	0.142 0.270	0.384	Vdc
Forward Transconductance (Note 3.)	$(V_{DS} = 8.0 \text{ Vdc}, I_{D} = 1.5 \text{ Adc})$	9fs	-	1.8	-	Mhos
DYNAMIC CHARACTERISTICS				•		
Input Capacitance		C _{iss}	-	200	280	pF
Output Capacitance	$(V_{DS} = 25 \text{ Vdc}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz)	C _{oss}	-	68	100	
Transfer Capacitance	·,	C _{rss}	_	26	40	
SWITCHING CHARACTERISTICS	S (Note 4.)					
Turn-On Delay Time		^t d(on)	-	9.2	20	ns
Rise Time	$(V_{DD} = 30 \text{ Vdc}, I_{D} = 2.0 \text{ Adc},$	t _r	-	9.2	20	
Turn-Off Delay Time	$V_{GS} = 10 \text{ Vdc},$ $R_{G} = 9.1 \Omega) \text{ (Note 3.)}$	td(off)	_	16	40	
Fall Time		t _f	_	9.2	20	
Gate Charge	(V _{DS} = 48 Vdc, I _D = 2.0 Adc, V _{GS} = 10 Vdc) (Note 3.)	QT	-	6.9	14	nC
		Q ₁	-	1.4	-	
		Q ₂	ı	3.0	_	
SOURCE-DRAIN DIODE CHARA	CTERISTICS					
Forward On-Voltage	$(I_S = 2.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$ $(I_S = 2.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc},$ $T_J = 150^{\circ}\text{C}) \text{ (Note 3.)}$	V _{SD}	- -	0.86 0.70	1.0	Vdc
Reverse Recovery Time	(I _S = 2.0 Adc, V _{GS} = 0 Vdc,	t _{rr}	-	28.9	-	ns
		ta	-	19.1	-	
	$dl_S/dt = 100 A/\mu s)$ (Note 3.)	t _b	-	9.8	-	
Reverse Recovery Stored Charge	Q _{RR}	_	0.030	_	μС	

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

^{4.} Switching characteristics are independent of operating junction temperatures.

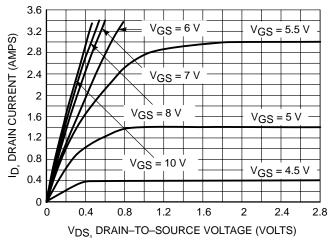


Figure 1. On-Region Characteristics

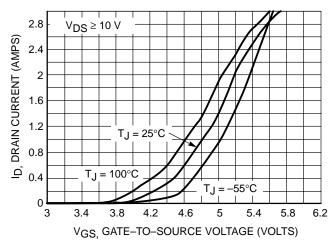


Figure 2. Transfer Characteristics

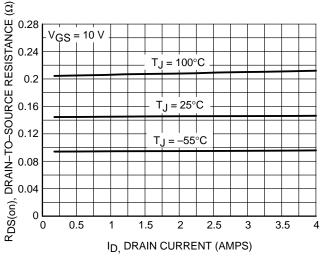


Figure 3. On-Resistance versus Gate-to-Source Voltage

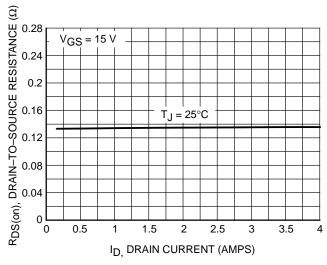


Figure 4. On-Resistance versus Drain Current and Gate Voltage

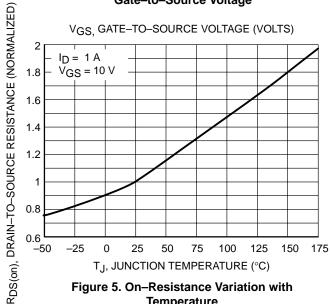


Figure 5. On-Resistance Variation with **Temperature**

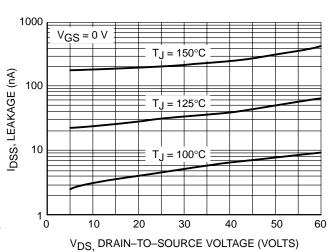


Figure 6. Drain-to-Source Leakage Current versus Voltage

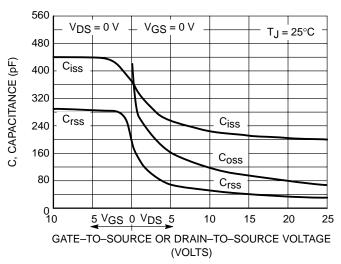


Figure 7. Capacitance Variation

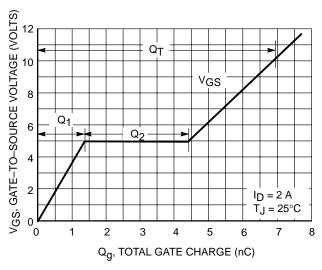


Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

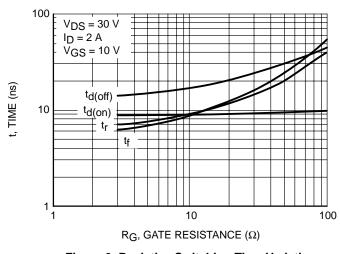


Figure 9. Resistive Switching Time Variation versus Gate Resistance

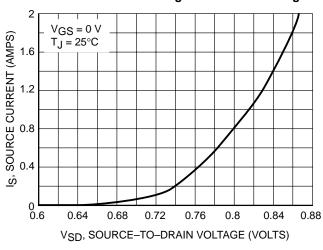


Figure 10. Diode Forward Voltage versus Current

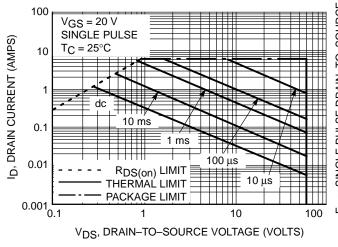


Figure 11. Maximum Rated Forward Biased Safe Operating Area

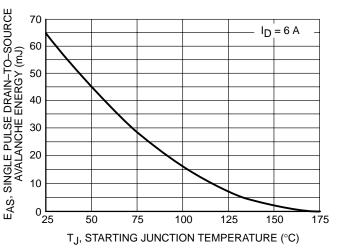


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

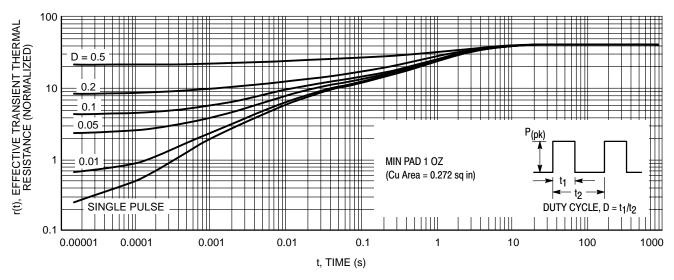
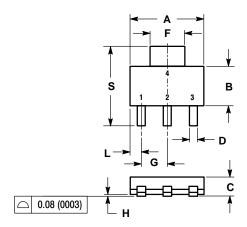


Figure 13. Thermal Response

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE K





NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.249	0.263	6.30	6.70	
В	0.130	0.145	3.30	3.70	
С	0.060	0.068	1.50	1.75	
D	0.024	0.035	0.60	0.89	
F	0.115	0.126	2.90	3.20	
G	0.087	0.094	2.20	2.40	
Н	0.0008	0.0040	0.020	0.100	
J	0.009	0.014	0.24	0.35	
K	0.060	0.078	1.50	2.00	
Ĺ	0.033	0.041	0.85	1.05	
M	0 °	10 °	0 °	10 °	
S	0.264	0.287	6.70	7.30	

- STYLE 3:
 PIN 1. GATE
 2. DRAIN
 3. SOURCE
 4. DRAIN



ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 Email: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.

NTF3055-160/D